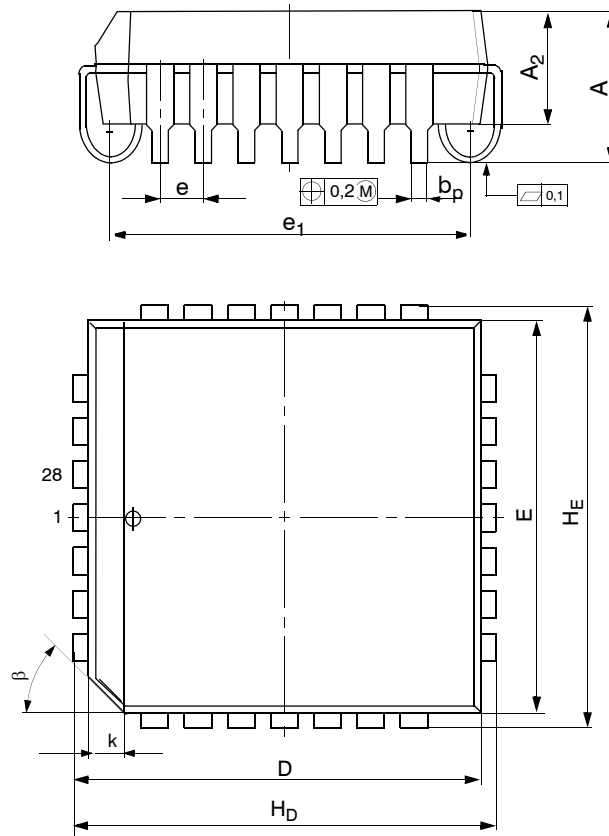


Dimensions in millimetres

Based on IEC 191-2Q: Type 112E08

## 1 Dimensions



Dimensions of Sub-Group B1	
$A_{\max}$	4,60
$b_{P\min}$	0,33
$b_{P\max}$	0,53
$e_{\text{nom}}$	1,27
$H_{D\min}$	12,30
$H_{D\max}$	12,67
$H_{E\min}$	12,30
$H_{E\max}$	12,67

- 2 Weight  $\leq 1,2$  g
- 3 Package Body Material Low Stress Epoxy
- 4 Lead Material FeNi-Alloy or Cu-Alloy
- 5 Lead Finish solder plating
- 6 Lead Form J-bends

Dimensions of Sub-Group C1	
$A_{\min}$	4,19
$A_{2\min}$	3,10
$A_{2\max}$	3,96
$D_{\min}^*$	11,40
$D_{\max}^*$	11,60
$E_{\min}^*$	11,40
$E_{\max}^*$	11,60
$k_{\min}$	1,00
$\beta$	45°
$e_{1\min}$	9,90
$e_{1\max}$	10,95

\*without mold-flash

Zentrum Mikroelektronik Dresden AG		
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